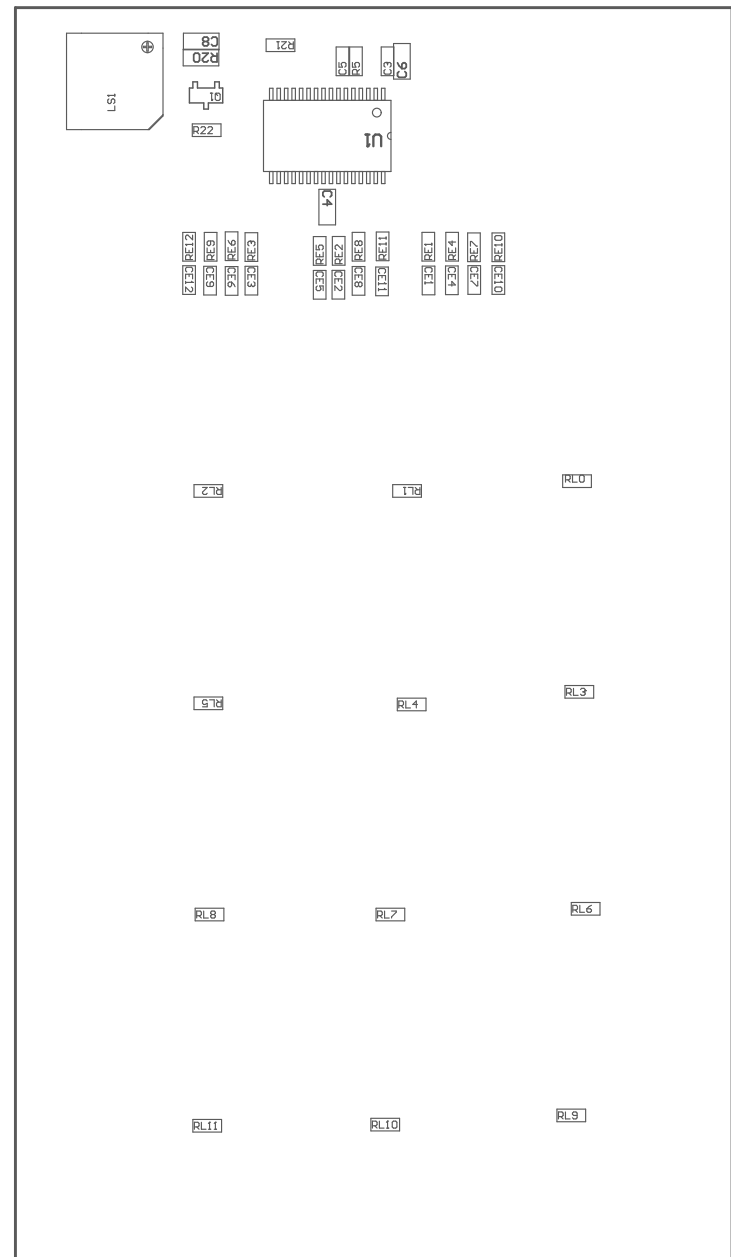


PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
	TID #: TIDM-1021		
PLOT NAME = Top Assembly Drawing	GENERATED : 7/19/2018 6:58:39 PM	TEXAS INSTRUMENTS	



PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
	TID #: TIDM-1021		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/19/2018	6:58:40 PM	TEXAS INSTRUMENTS

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